

REMARKS

The foregoing amendment is requested in order to conform to claims in the application submitted herewith. The additional numerical values are supported by the excerpt (pages 612-616) from the Electronic Materials Handbook published by ASM International, attached to the declaration submitted herewith by co-inventor Ronald W. Gedney.

These materials demonstrate that, at the time of the application for U.S. Patent 5,483,421, Mr. Gedney and others skilled in electronic packaging materials knew that the coefficient of thermal expansion for glass-filled epoxy dielectric materials suitable for electronic packaging could be 15×10^{-6} ppm/°C or less. Thus, these values for coefficients of thermal expansion are inherent in the disclosure of glass filled epoxy dielectric material and the addition of these values in this application should not be considered new matter.

Respectfully submitted,

By: 

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